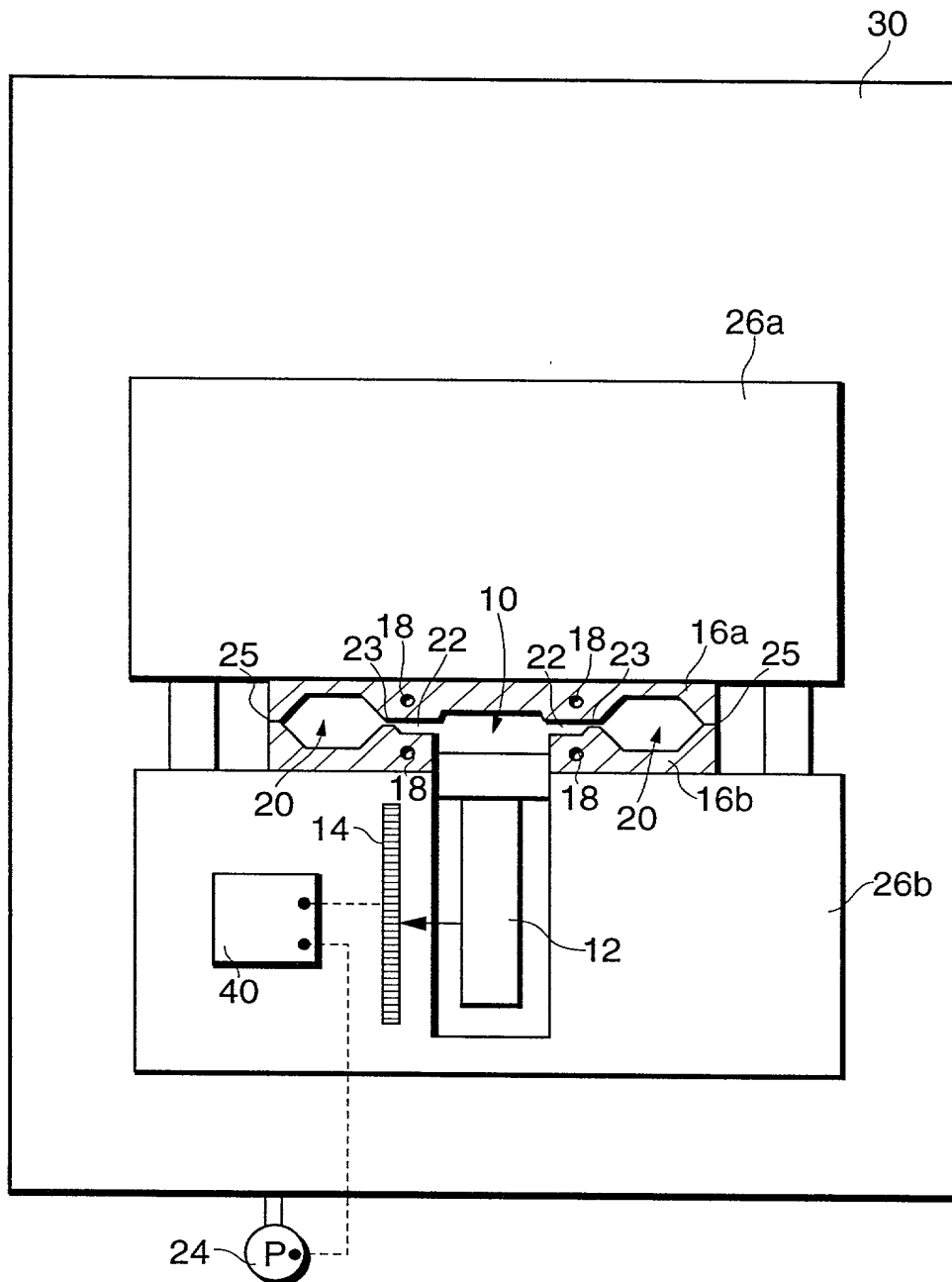


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**Fig. 1**



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Fig. 2(a)

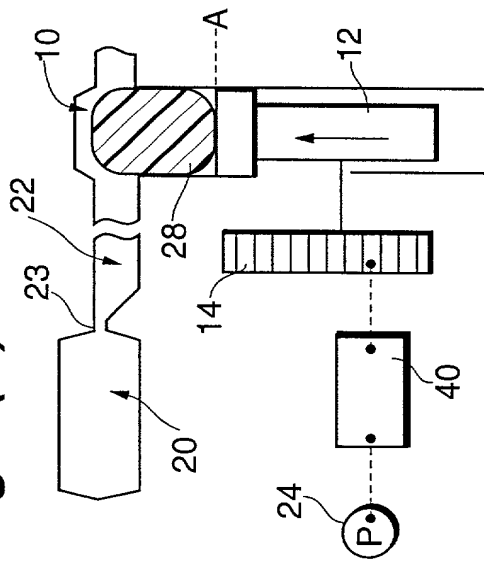


Fig. 2(b)

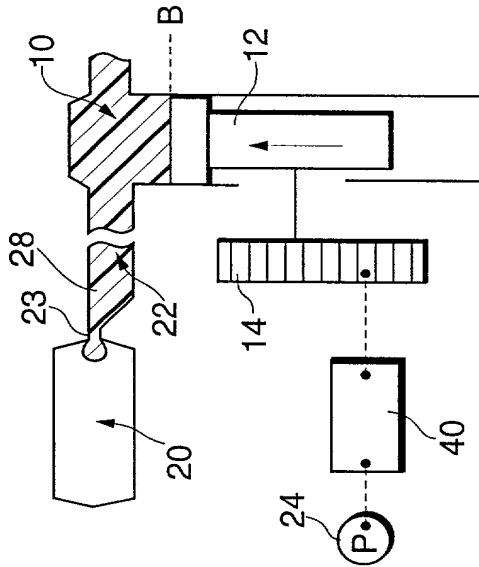


Fig. 2(c)

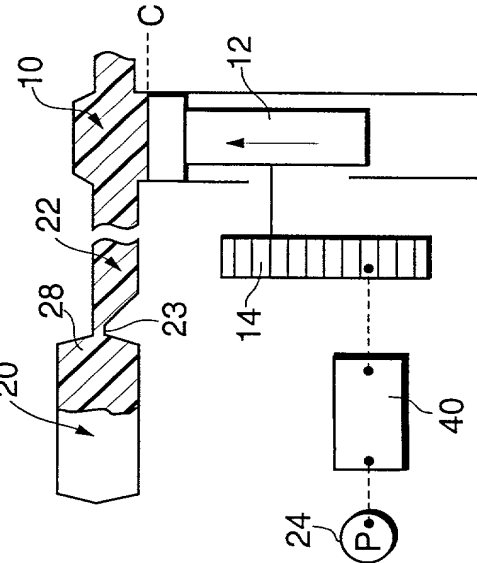
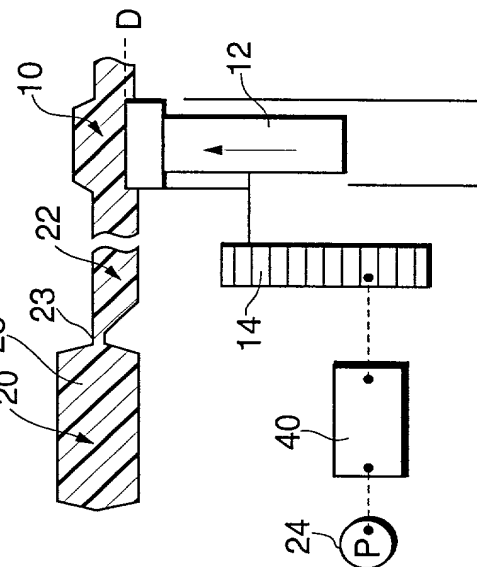
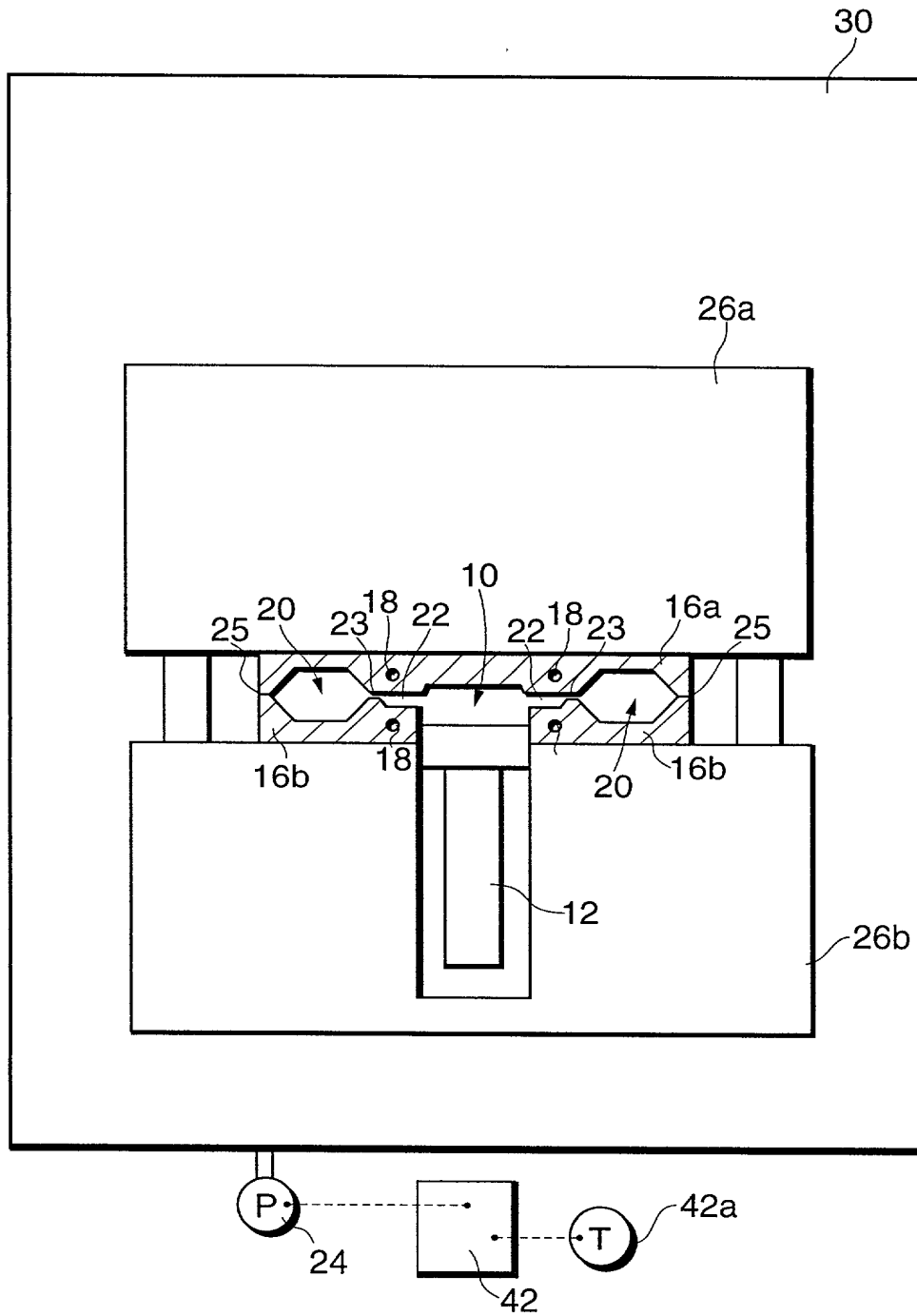


Fig. 2(d)



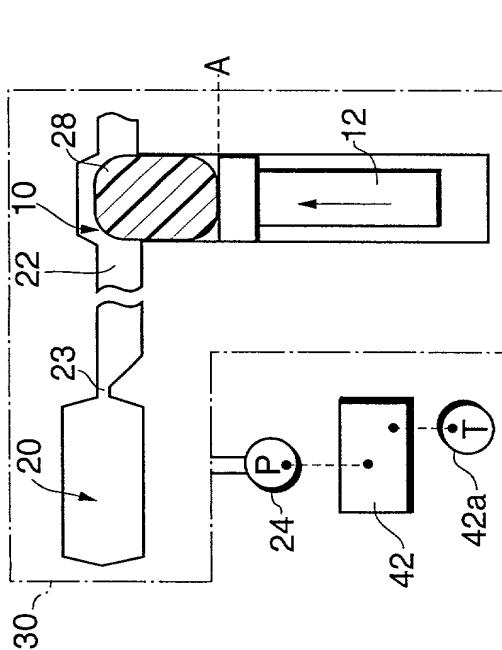
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**Fig.3**

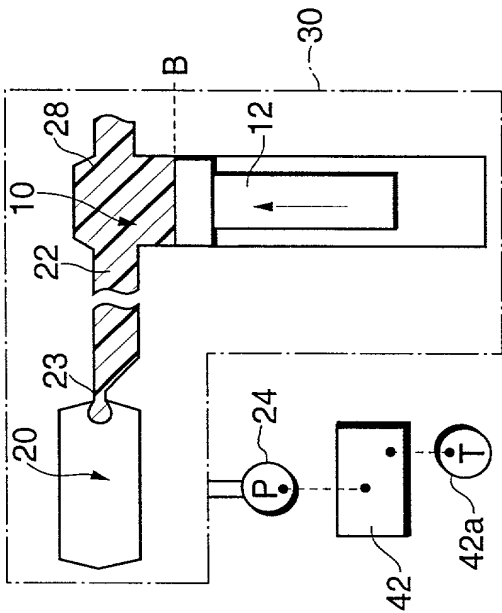


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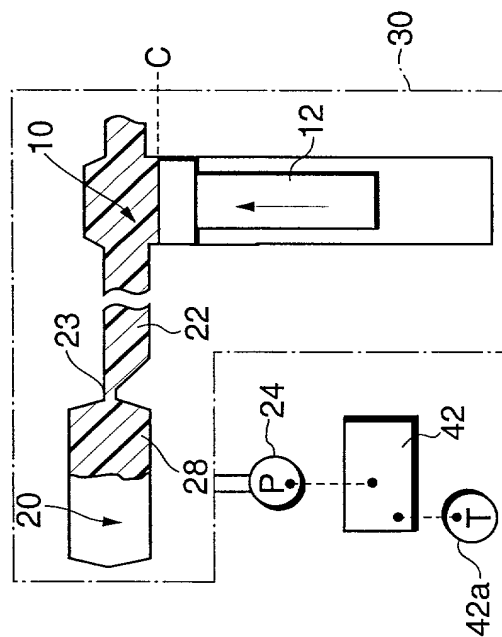
**Fig. 4(a)**



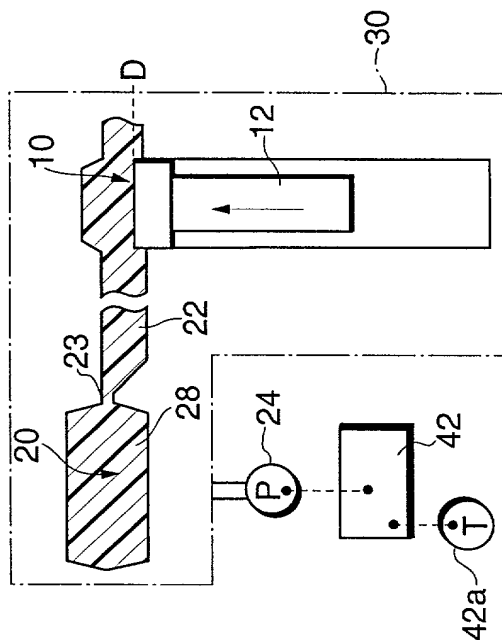
**Fig. 4(b)**



**Fig. 4(c)**

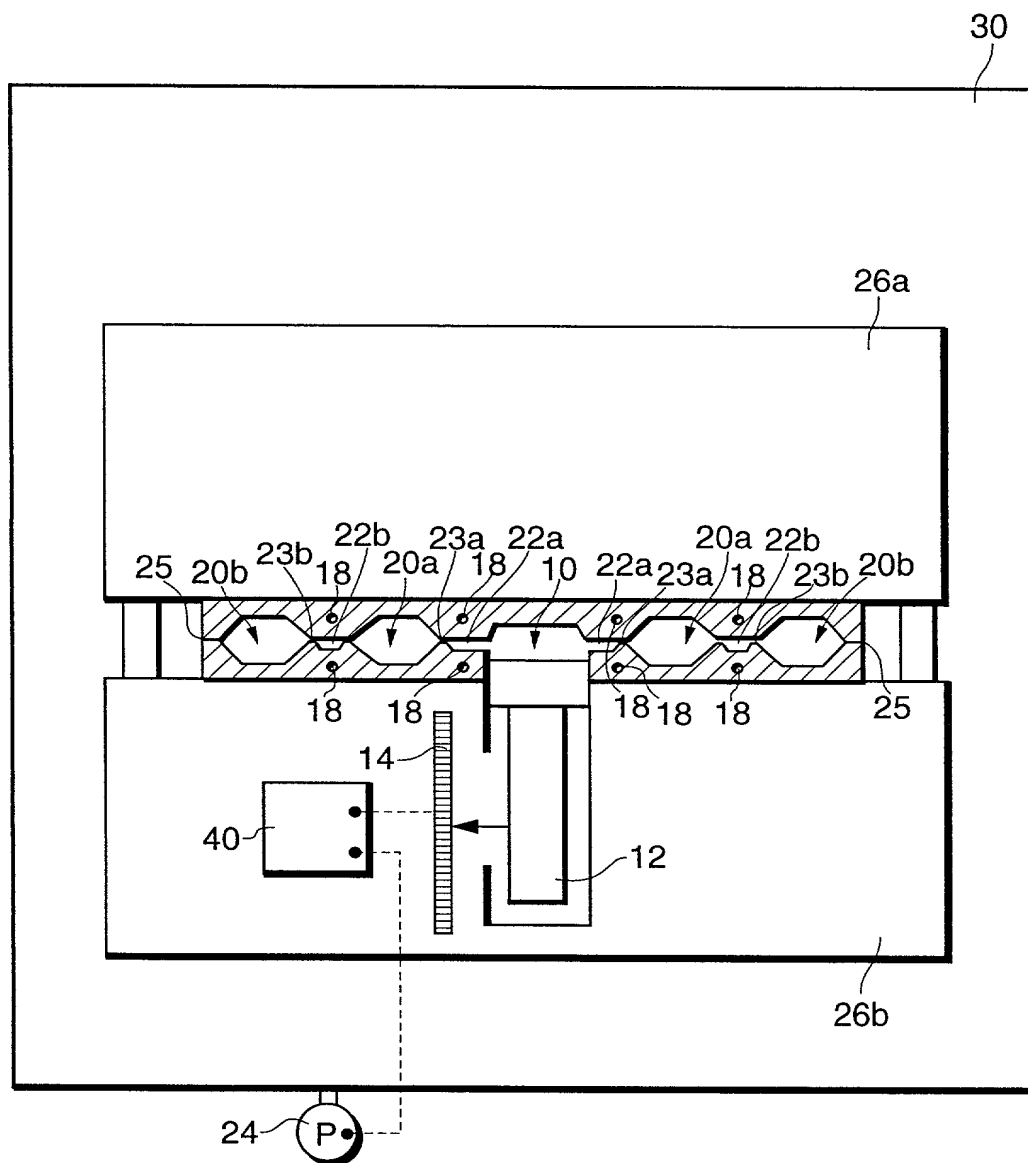


**Fig. 4(d)**



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**Fig.5**



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Fig. 6(b)

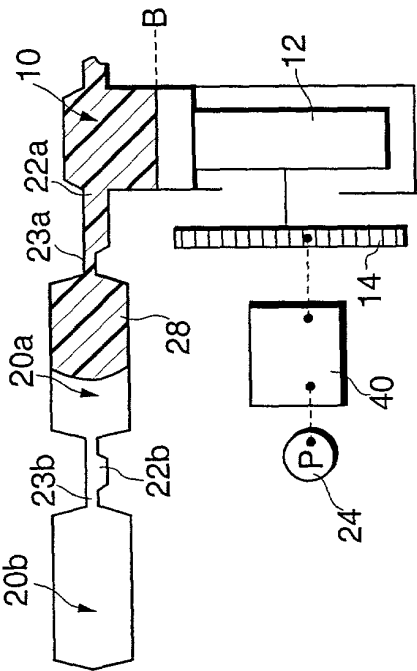


Fig. 6(d)

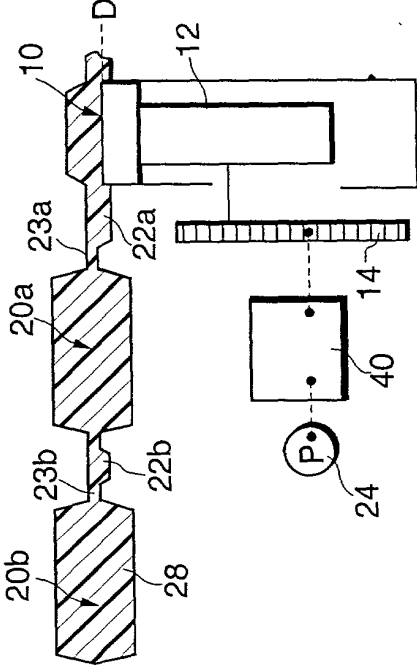


Fig. 6(a)

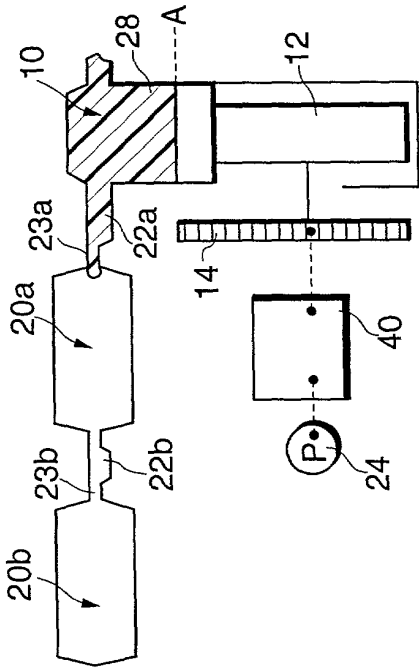
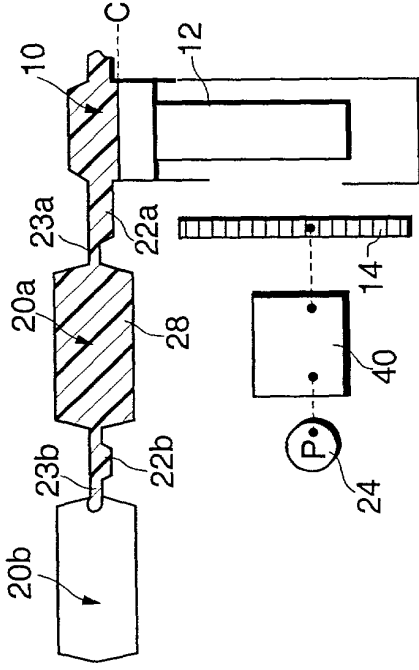
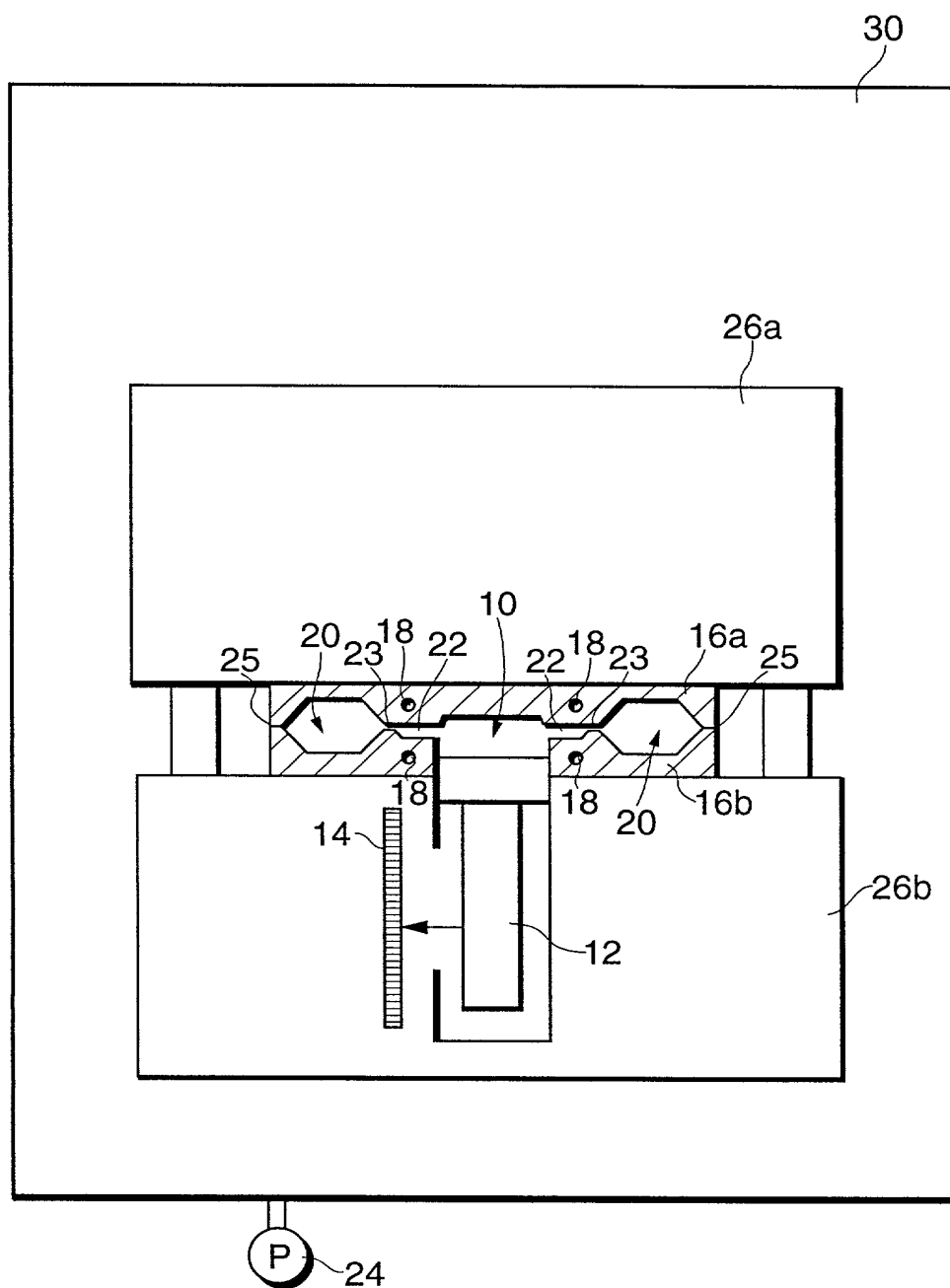


Fig. 6(c)



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**Fig.7**



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